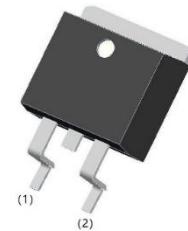


V_{RRM} = 650 V

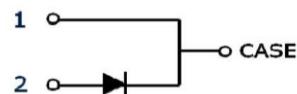
$I_F(T_c=150^\circ\text{C})$ = 5 A

Q_c = 11.3 nC



Features:

- Extremely low reverse current
- No reverse recovery current
- Temperature independent switching
- Positive temperature coefficient on V_F
- Excellent surge current capability
- Low Capacitive charge



Benefits

- Essentially No switching losses
- System efficiency improvement over Si Diodes
- Increased power density
- Enabling higher switching frequency
- Reduction of Heat Sink Requirements
- System Cost savings due to smaller magnetics
- Reduced EMI



Applications

- Switch Mode Power Supplies (SMPS)
- Uninterruptable power supplies
- Motor Drivers
- Power Factor Correction

Pacakge Pin definitions

- Pin1-Cathode
- Pin2-Anode

Package Parameters

Part Number	Marking	Package
B1D04065F	B1D04065F	TO-263-2L

Maximum ratings

Symbol	Parameter	Test conditions	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage		650	V
V_{RSM}	Surge Peak Reverse Voltage		650	V
I_F	Continuous Forward Current	$T_c=25^\circ C$ $T_c=135^\circ C$ $T_c=150^\circ C$	14 6 5	A
I_{FSM}	Non-Repetitive Forward Surge Current	$T_c=25^\circ C, t_p=10ms$, sine halfwave	32	A
$\int i^2 dt$	$i^2 t$ Value	$T_c=25^\circ C, t_p=10ms$	6.12	A ² S
P_{tot}	Power Dissipation	$T_c=25^\circ C$ $T_c=110^\circ C$	68 29	W
T_j	Operating junction temperature		-55~175	°C
T_{stg}	Storage temperature		-55~135	°C

Thermal Characteristics

Symbol	Parameter	Value			Unit
		Min.	Typ.	Max.	
$R_{th(jc)}$	Thermal resistance from junction to case		2.20		K/W
$R_{th(ja)}$	Thermal resistance from junction to ambient		71.52		K/W

Electrical Characteristics

Static Characteristics ($T_j=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test conditions	Value			Unit
			Min.	Typ.	Max.	
V_{DC}	DC blocking voltage	$T_j=25^\circ\text{C}$	650			V
V_F	Diode forward voltage	$I_F=4\text{A } T_j=25^\circ\text{C}$ $I_F=4\text{A } T_j=175^\circ\text{C}$		1.45 1.9		V
I_R	Reverse current	$V_R=650\text{V } T_j=25^\circ\text{C}$ $V_R=650\text{V } T_j=175^\circ\text{C}$		0.05 3		μA

Dynamic Characteristics ($T_j=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test conditions	Value			Unit
			Min.	Typ.	Max.	
Q_c	Total capacitive charge	$V_R=400\text{V } T_j=25^\circ\text{C}$ $Q_c = \int_0^{V_R} C(V)dV$		11.3		nC
C	Total Capacitance	$V_R=1\text{V } f=1\text{MHz}$ $V_R=300\text{V } f=1\text{MHz}$ $V_R=600\text{V } f=1\text{MHz}$		177 28.6 28.4		pF

Typical Performance

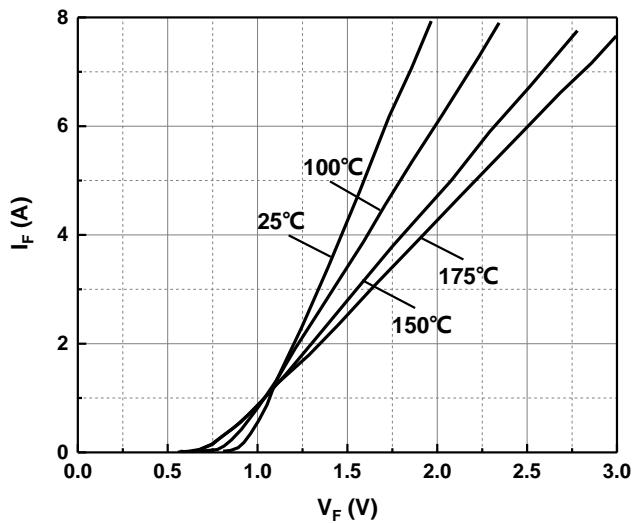


Figure 1. Typical forward characteristics

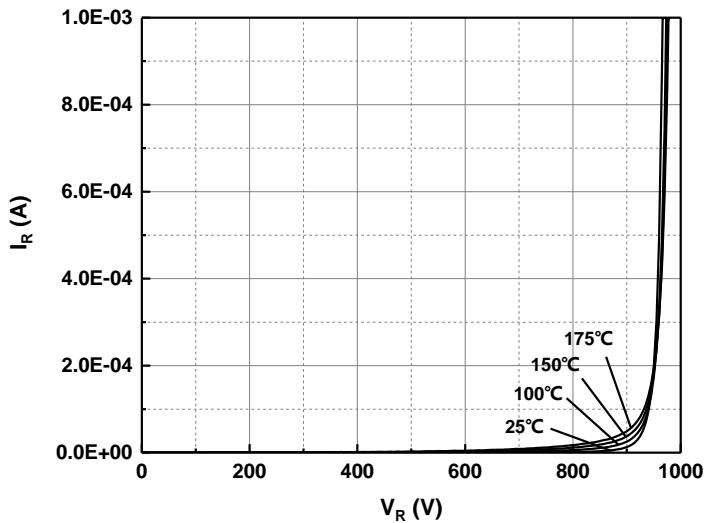


Figure 2. Typical reverse current as function of reverse voltage

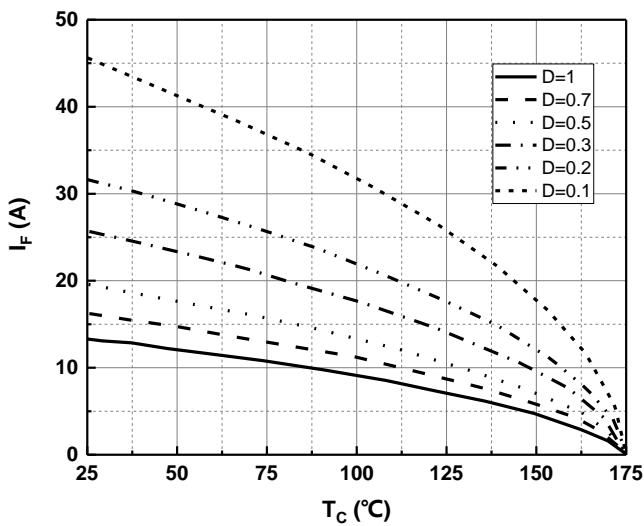


Figure 3. Diode forward current as function of temperature, D=duty cycle

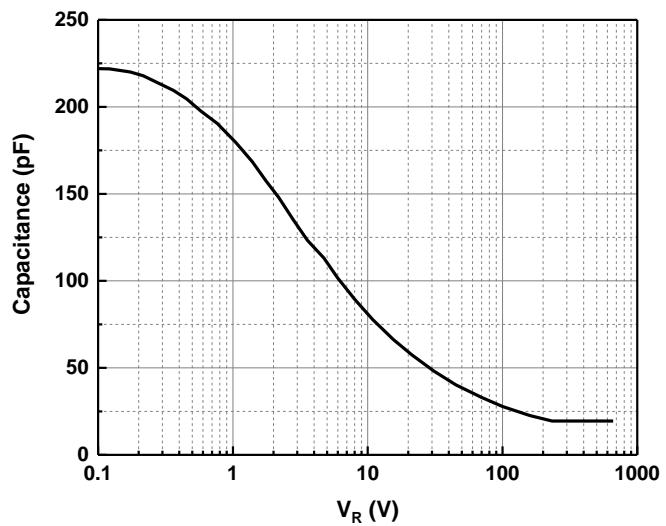


Figure 4. Typical capacitance as function of reverse voltage, $C=f(V_R)$; $T_j=25^\circ\text{C}$; $f=1 \text{ MHz}$

Typical Performance

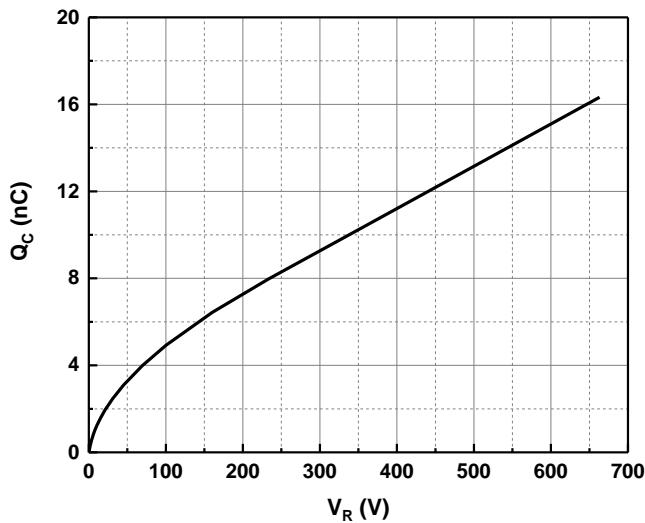


Figure 5. Typical reverse charge as function of reverse voltage

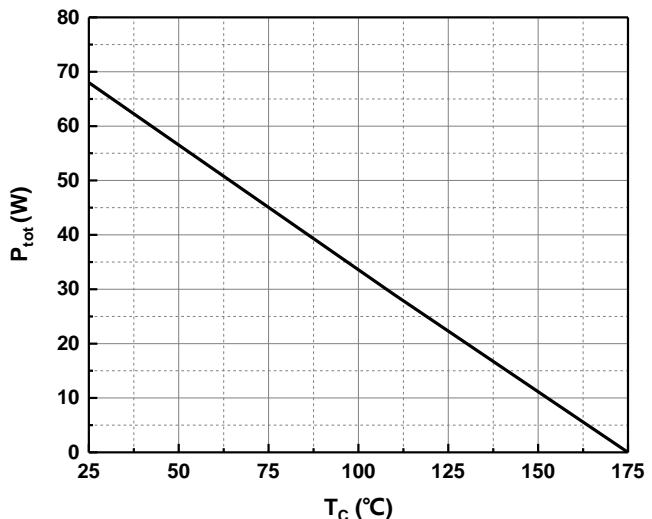


Figure 6. Power dissipation as function of case temperature

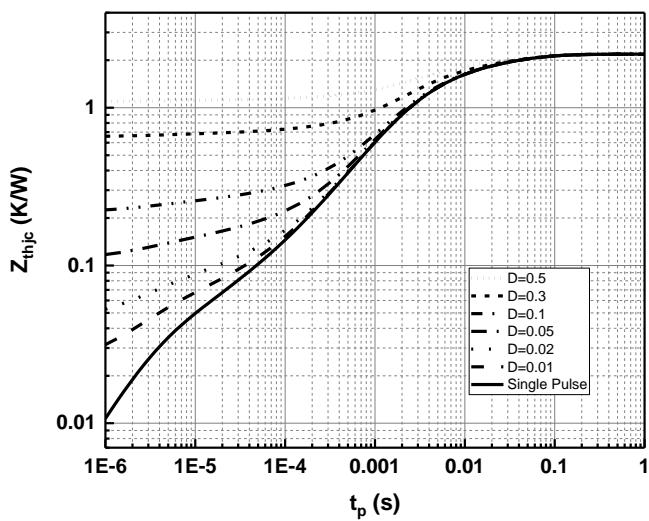
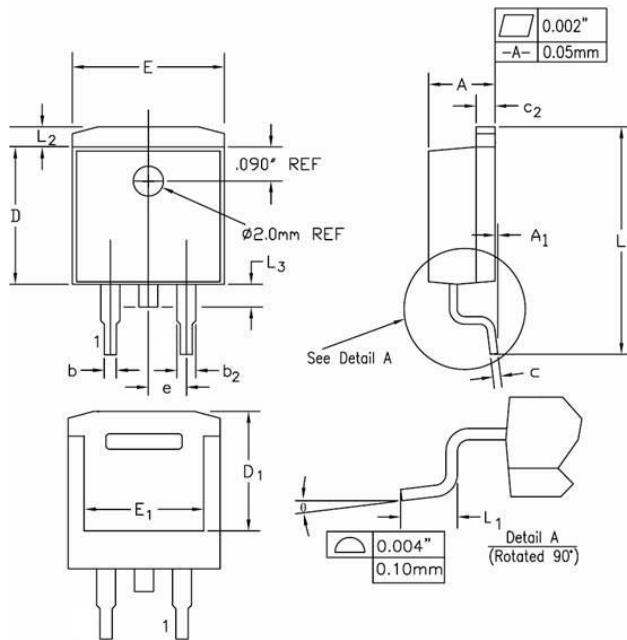


Figure 7. Max. transient thermal impedance, $Z_{th,jc}=f(t)$, parameter: $D=t/T$

Package Dimensions


POS	Inches		Millimeters	
	Min	Max	Min	Max
A	0.17	0.18	4.32	4.57
A1	-	0.01	-	0.25
b	0.028	0.037	0.71	0.94
b2	0.045	0.055	1.15	1.4
c	0.014	0.025	0.356	0.635
c2	0.048	0.055	1.22	1.4
D	0.35	0.37	8.89	9.4
D1	0.255	0.324	6.48	8.23
E	0.395	0.405	10.04	10.28
E1	0.31	0.318	7.88	8.08
e	0.1	BSC.	2.54	BSC.
L	0.58	0.62	14.73	15.75
L1	0.09	0.11	2.29	2.79
L2	0.045	0.055	1.15	1.39
L3	0.05	0.07	1.27	1.77
θ	0°	8°	0°	8°

Revision History

Version: Preliminary Version

Previous Revision

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Information

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